TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (DTMOS)

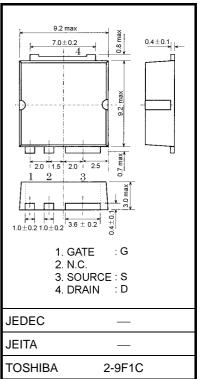
TK20X60U

Switching Regulator Applications

- Low drain-source ON resistance: RDS (ON) = 0.165 (typ.)
- High forward transfer admittance: $|Y_{fs}| = 12 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 100 \ \mu A (V_{DS} = 600 \text{ V})$
- Enhancement-mode: $V_{th} = 3.0 \sim 5.0 \text{ V}$ (VDS = 10 V, ID = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	20		
	Pulse (t = 1 ms) (Note 1)	I _{DP}	40	A	
Drain power dissipation (Tc = 25°C)		PD	150	W	
Single pulse avalanche energy (Note 2)		E _{AS}	144	mJ	
Avalanche current (Note 3)		I _{AR}	20	А	
Repetitive avalanche energy		E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 0.74 g (typ.)

Thermal Characteristics

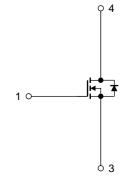
Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W	

Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2: $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 0.63 mH, R_G = 25 , I_{AR} = 20 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.



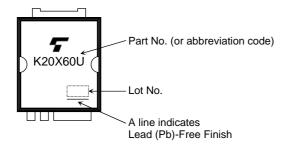
Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$		—	±1	μA
Drain cut-off current		I _{DSS}	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	100	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	_		V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	3.0	_	5.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		0.165	0.19	Ω
Forward transfer	nsfer admittance $ Y_{fs} $ $V_{DS} = 10 \text{ V}, I_D = 10 \text{ A}$		$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	3	12		S
Input capacitance		C _{iss}			1470		
Reverse transfer capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	_	150		pF
Output capacitance		C _{oss}			3500		
Switching time	Rise time	tr	V_{GS} $I_D = 10A$ V_{OUT}		40		
	Turn-on time	t _{on}	$ \begin{array}{c} $		80		. ns
	Fall time	t _f			12	_	
	Turn-off time	t _{off}	Duty \leq 1%, t _W = 10 μ s		100	_	
Total gate charge		Qg			27		
Gate-source charge		Q _{gs}	$V_{DD}\simeq 400~V,~V_{GS}=10~V,~I_{D}=20~A$		16		nC
Gate-drain charge		Q _{gd}	1	_	11	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	20	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	40	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 20 \text{ A}, V_{GS} = 0 \text{ V},$	_	450	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs		8.1		μC

Marking



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20070701-EN

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